

## SPECIFICATIONS

item	unit	specification	condition
oscillation frequency	Hz	4000	Vo-p=1/2 duty, square wave
operating voltage	Vo-p	2 ~ 4	
rated voltage	Vo-p	3	
current consumption	mA	MAX. 90	at Rated Voltage
sound pressure level	dB	MIN. 70	at 10 cm at Rated Voltage
coil resistance	Ω	17±3	
operating temperature	°C	-20 ~ +70	
storage temperature	°C	-30 ~ +80	
dimension	mm	4.0 x 4.0 x H2.0	See appearance drawing
weight	gram	0.1	
housing material		LCP( Black )	
leading pin	SMD type	Tin Plated Brass(Sn)	See appearance drawing
environmental		RoHS	
protection regulation			

## **RELIABILTY TEST**

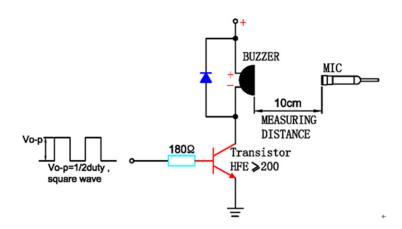
item	test condition	requirement
high temperature test (storage)	After being placed in a chamber with $80 \pm 2^{\circ}$ C for 96 hours and then being placed in normal condition for 2 hours.	Allowable variation of SPL after test: $\pm 10$ dB.
low temperature test (storage)	After being placed in a chamber with $-30 \pm 2^{\circ}$ C for 96 hours and then being placed in normal condition for 2 hours.	Allowable variation of SPL after test: $\pm 10$ dB.
humidity test	After being placed in a chamber with 90 $\sim$ 95% R.H. at 40 $\pm$ 2°C for 96 hours and then being placed in normal condition for 2 hours.	Allowable variation of SPL after test: ±10dB.
temperature cycle test	The part will be subjected to 5 cycles. One cycle shall be consist of: +70°C +25°C +25°C 	Allowable variation of SPL after test: ±10dB.
drop test	Drop on a hard wood board of 4cm thick, any directions ,6 times, at the height of 75cm.	Allowable variation of SPL after test: $\pm 10$ dB.
vibration test	After being applied vibration of amplitude of 1.5mm with 10Hz to 55 Hz band of vibration frequency to each of 3 perpendicular directions for 2 hours.	Allowable variation of SPL after test: $\pm 10$ dB.
solderability test	Lead terminals are immersed in rosin for 5 seconds and then immersed in solder bath of $+300 \pm 5$ °C for 3 $\pm 1$ seconds.	
terminal strength pulling test	The force of 9.8N(1.0kg) is applied to each terminal in axial direction for 10 seconds.	No visible damage and cutting off.
<b>TEST CONDITION</b> Standard Test Condition	a) Temperature : +5 ~ +35°C b) Humidity : 45-85% c) Pres	sure : 860-1060mbar



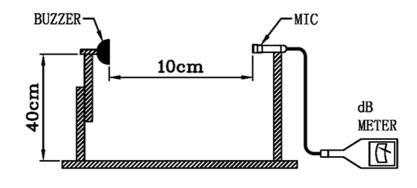
## **TESTING METHOD**

#### **STANDARD MEASUREMENT CONDITIONS** Temperature: 25 ±2 °C Humidity: 45 ~ 65%

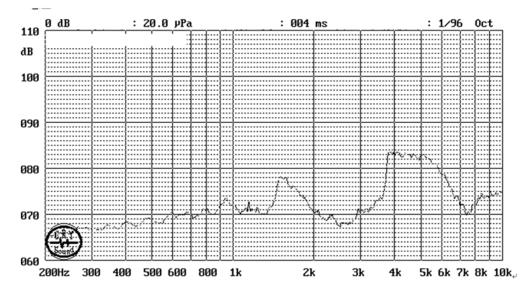
**ACOUSTIC CHARACTERISTICS** The oscillation frequency, current consumption and sound pressure are measured by the measuring instruments shown below



In the measuring test, buzzer is placed as follows:

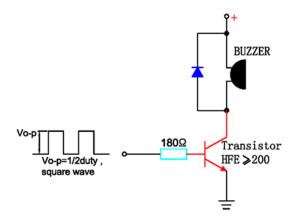


#### **TYPICAL FREQUENCY RESPONSE CURVE**





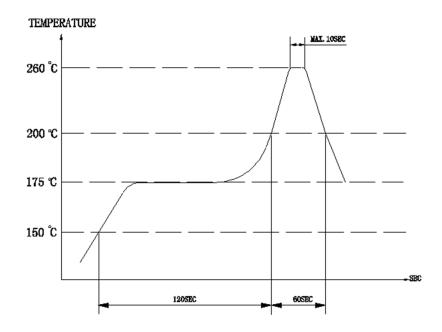
## **RECOMMENDED DRIVING CIRCUIT**



The base current Ib should high enough so that it saturates the collector current of the transistor with the CB load.

## SOLDERING CONDITIONS

- 1. Recommendable reflow soldering condition is as follows (Reflow soldering is twice)
- Note: It is requested that reflow soldering should be executed after heat of product goes down to normal.



Heat resistant line (Used when heat resistant reliability test is performed)

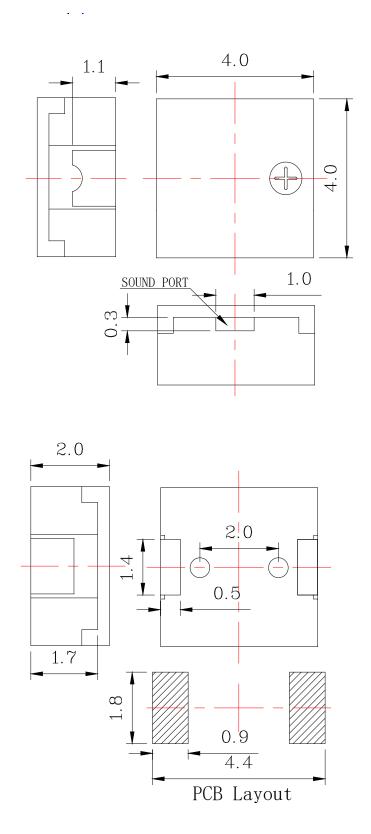
2. Manual soldering: Manual soldering temperature 350 °C within 5 sec.



# DRAWING

Tolerance: ±0.3 Unit:mm

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## PACKING STANDARD

